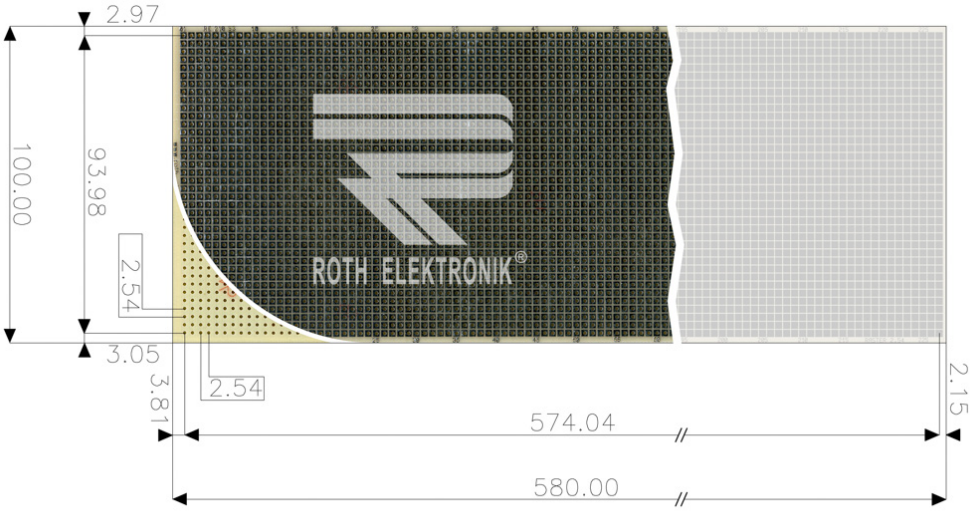

RE210-S3

- Fibre-glass CEM3 1.50 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL-leadfree)
- Hole spacing 2.54 x 2.54 mm
- 38 x 227 soldering pads 2.20 x 2.20 mm
- Hole diameter 1.00 mm
- Size 100 x 580 mm

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